UMH8NFHA / IMH8AFRA

NPN 100mA 50V Complex Digital Transistors (Bias Resistor Built-in Transistors)

Datasheet

AEC-Q101 Qualified

Parameter	Tr1 and Tr2
$V_{\sf CEO}$	50V
I _C	100mA
R ₁	10kΩ

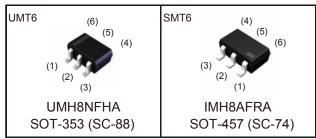
Features

- 1) Built-In Biasing Resistors.
- 2) Two DTC114T chips in one package.
- 3) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see inner circuit).
- 4) The bias resistors consist of thin-film resistors with complete isolation to allow negative biasing of the input. They also have the advantage of completely eliminating parasitic effects.
- 5) Only the on/off conditions need to be set for operation, making the circuit design easy.
- 6) Lead Free/RoHS Compliant.

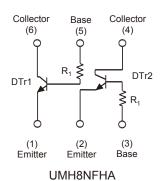
Application

Inverter circuit, Interface circuit, Driver circuit

Outline



•Inner circuit



Base Emitter (6)

DTr2

R₁

DTr1

(3)

Collector Base Collector

IMH8AFRA

Packaging specifications

Part No.	Package	Package size (mm)	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit (pcs)	Marking
UMH8NFHA	UMT6	2021	TR	180	8	3,000	H8
IMH8AFRA	SMT6	2928	T108	180	8	3,000	H8

●Absolute maximum ratings (Ta = 25°C)

<For DTr1 and DTr2 in common>

Parameter		Symbol	Values	Unit
Collector-base voltage		V_{CBO}	50	V
Collector-emitter voltage		V _{CEO}	50	V
Emitter-base voltage		V_{EBO}	5	V
Collector current		I _C *1	100	mA
Collector Power dissipation UMH8NFHA IMH8AFRA		P _D *2	150 (Total) ^{*3}	mW
		T FD	300 (Total)*4	mW
Junction temperature		Tj	150	°C
Range of storage temperature		T _{stg}	−55 to +150	°C

●Electrical characteristics(Ta = 25°C)

<For DTr1 and DTr2 in common>

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Collector-base breakdown voltage	BV _{CBO}	I _C = 50μA	50	-	-	V
Collector-emitter breakdown voltage	BV _{CEO}	I _C = 1mA	50	-	-	V
Emitter-base breakdown voltage	BV_{EBO}	I _E = 50μA	5	-	-	V
Collector cut-off current	I _{CBO}	V _{CB} = 50V	-	-	0.5	μА
Emitter cut-off current	I _{EBO}	V _{EB} = 4V	-	-	0.5	μА
Collector-emitter saturation voltage	V _{CE(sat)}	I _C / I _B = 10mA / 1mA	-	-	0.3	V
DC current gain	h _{FE}	V_{CE} = 5V , I_{C} = 1mA	100	250	600	-
Input resistance	R ₁	-	7	10	13	kΩ
Transition frequency	f _T *1	$V_{CE} = 10V, I_{E} = -5mA$ f = 100MHz	-	250	-	MHz

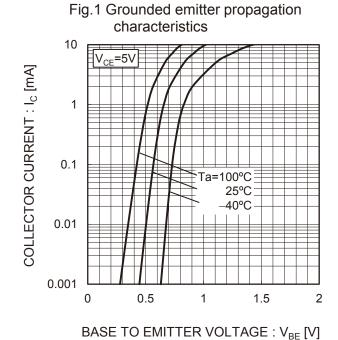
^{*1} Characteristics of built-in transistor

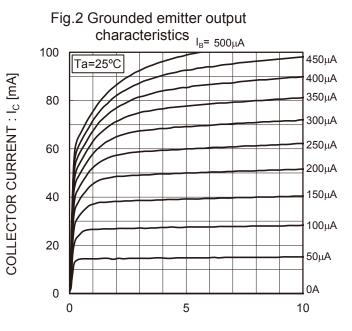
^{*2} Each terminal mounted on a reference footprint

^{*3 120}mW per element must not be exceeded.

^{*4 200}mW per element must not be exceeded.

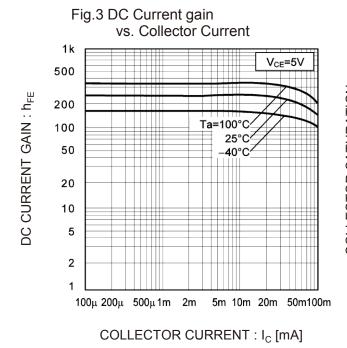
●Electrical characteristic curves (Ta = 25°C) <For DTr1 and DTr2 in common>





COLLECTOR TO EMITTER VOLTAGE: V_{CE} [V]

Fig.4 Collector-emitter saturation voltage

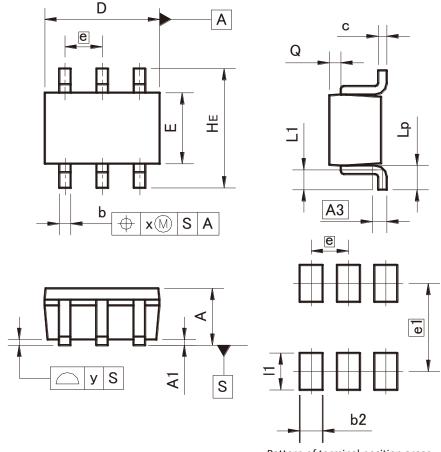


vs. Collector Current 1 $I_{\rm C}/I_{\rm B}=10$ 500m COLLECTOR SATURATION VOLTAGE: V_{CE(sat)} [V] 200m 100m Ta=100°C 25°C 50m 20m 10m 5m 2m 1m $100 \mu \ 200 \mu \ \ 500 \mu \ 1m \ \ \ 2m$ 5m 10m 20m 50m100m

COLLECTOR CURRENT: Ic [mA]

●Dimensions (Unit : mm)





Pattern of terminal position areas [Not a recommended pattern of soldering pads]

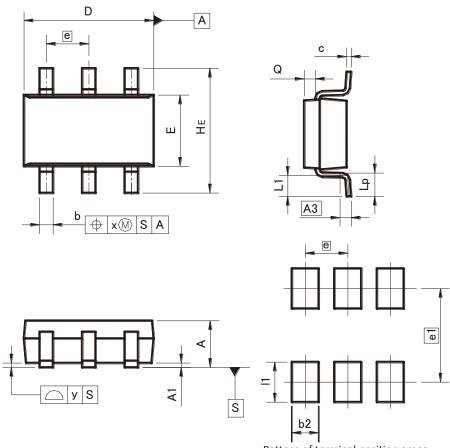
DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	0.80	1.00	0.031	0.039
A1	0.00	0.10	0.000	0.004
A3	0.3	25	0.0	10
b	0.15	0.30	0.006	0.012
С	0.10	0.20	0.004	0.008
D	1.90	2.10	0.075	0.083
E	1.15	1.35	0.045	0.053
е	0.65		0.0	26
HE	2.00	2.20	0.079	0.087
L1	0.20	0.50	0.008	0.020
Lp	0.25	0.55	0.010	0.022
Q	0.10	0.30	0.004	0.012
Х	_	0.10	_	0.004
У	_	0.10	_	0.004

DIM	MILIMI	ETERS	INCHES	
MIN		MAX	MIN	MAX
b2	_	0.40	_	0.016
e1	1.55		0.0	61
l1	_	0.65	-	0.026

Dimension in mm / inches

●Dimensions (Unit : mm)





Pattern of terminal position areas
[Not a recommended pattern of soldering pads]

DIM MILIN		ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
A3	0.5	25	0.0	10
b	0.25	0.40	0.010	0.016
С	0.09	0.25	0.004	0.010
D	2.80	3.00	0.110	0.118
E	1.50	1.80	0.059	0.071
е	0.9	0.95 0.037		37
HE	2.60	3.00	0.102	0.118
L1	0.30	0.60	0.012	0.024
Lp	0.40	0.70	0.016	0.028
Q	0.20	0.30	0.008	0.012
х	_	0.20	_	0.008
У	_	0.10	_	0.004

DIM	MILIMI	ETERS	INCHES	
DIM	MIN	MAX	MIN	MAX
b2		0.60	_	0.024
e1	2.10		0.0	83
l1	_	0.90	_	0.035

Dimension in mm / inches

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